

CNC 165: Root Cause Analysis in Die Repair

This course provides a theoretical and performance-based study on the process of root cause analysis used in repairing stamping dies, molds, fixtures, etc. Emphasis is placed on safety, identifying defects, finding the root cause, performing corrective actions, and prevention of problems. Upon completion, students should be able to understand how to identify and use root cause analysis, and troubleshooting methods to find correct and accurate solutions to die repair needs, and the measures to employ to correct problems while ensuring a long term fix.

Credits: 2

Transfer Code: Code C

Lab Hours: 2

Lecture Hours: 1

Prerequisites:

As determined by college.

Program: Computerized Numerical Control

Semester Offered:

Fall

Spring

Summer